

ABSTRACT

5 The invention relates to a method for forming patterns (11, 22) aligned on either side of a thin film (3) deposited on a substrate (1), said method comprising:

- depositing a first pattern layer (5) on the thin film (3), the deposition of the first pattern layer preceding
10 or following local etching of the thin film (3) in order to form a first marking,
- etching the first pattern layer in order to form a first pattern (11),
- depositing a first bonding layer (3) for covering
15 the first marking (8) and the first pattern (11),
- suppressing the substrate (1),
- etching the first bonding layer (13) in order to form a second marking (16) at the location of the first marking (8),
- 20 - depositing a second pattern layer (18), and
- etching the second pattern layer (18) in order to form the second pattern (22).

Fig. 11

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